

**Electronic Patent Application Fee Transmittal**

<b>Application Number:</b>	10580361			
<b>Filing Date:</b>	18-Apr-2007			
<b>Title of Invention:</b>	Production Of Semiconductor Substrates With Buried Layers By Joining (Bonding) Semiconductor Wafers			
<b>First Named Inventor/Applicant Name:</b>	Roy Knechtel			
<b>Filer:</b>	Robert L. Showalter/Sandy Moles			
<b>Attorney Docket Number:</b>	LEO 003 PA			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110